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Dr. Minsuk Suh received his bachelor's, master's and doctoral degrees of material science and engineering from KAIST. He has been involved in the development and mass production of RDL, Flip chip, WLCSP and TSV at SK hynix. In 2020, based on over 20 years of experience in the package industry, he wrote a book, 'Package and Test that adds value to Semiconductor', for package engineers as well as engineers at equipment, materials, and students studying packages.